

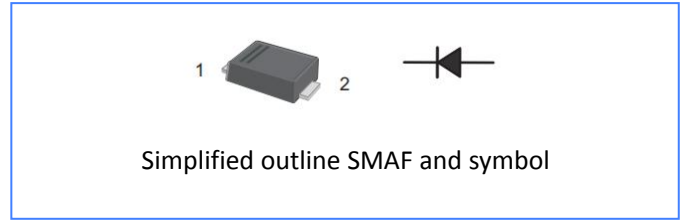
ES2AF THRU ES2JF

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

Mechanical Data

- Case:SMAF
- Terminals: Solderable per MIL-STD-750, Method2026
- Approx.Weight: 27mg / 0.00095oz



Pinning

PIN	DESCRIPTION
1	Cathode
2	Anode

Absolute Maximum Ratings And Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

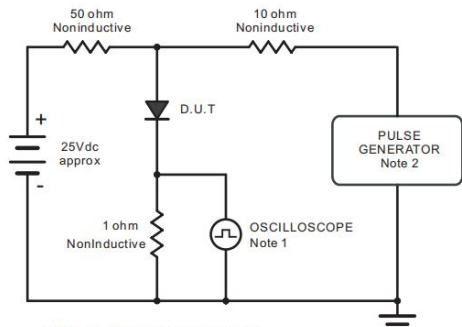
Parameter	Symbols	ES2AF	ES2BF	ES2CF	ES2DF	ES2EF	ES2GF	ES2JF	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current	I _{F(AV)}	2							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	50							A
Maximum Forward Voltage at 1 A	V _F	1.0				1.25		1.68	V
Maximum DC Reverse Current Ta = 25° C at Rated DC Blocking Voltage Ta =125° C	I _R	5 100							μ A
Typical Junction Capacitance at VR=4V, f=1MHz	Cj	30							pF
Maximum Reverse Recovery Time ⁽¹⁾	t _{rr}	35							ns
Typical Thermal Resistance ⁽²⁾	RθJA	65							°C/W
	RθJC	20							
Operating and Storage Temperature Range	T _J , T _{stg}	-55 ~ +150							°C

(1) Measured with $I_F = 0.5 \text{ A}$, $I_R = 1 \text{ A}$, $I_{rr} = 0.25 \text{ A}$

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas

Rating And Characteristic Curves

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

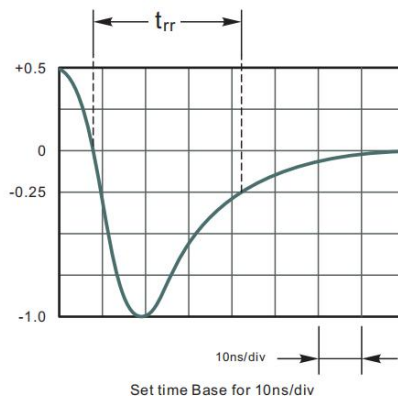


Fig.2 Maximum Average Forward Current Rating

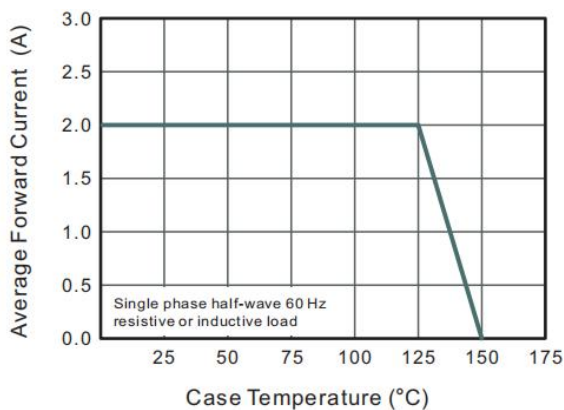


Fig.3 Typical Reverse Characteristics

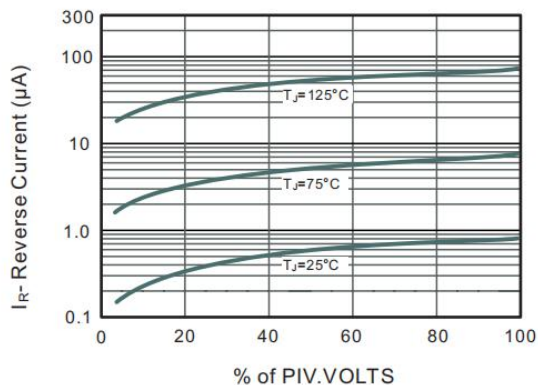


Fig.4 Typical Forward Characteristics

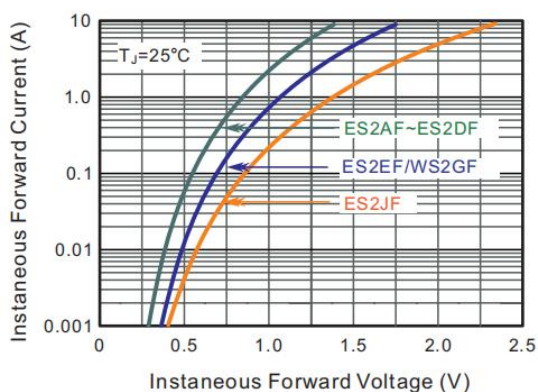


Fig.5 Typical Junction Capacitance

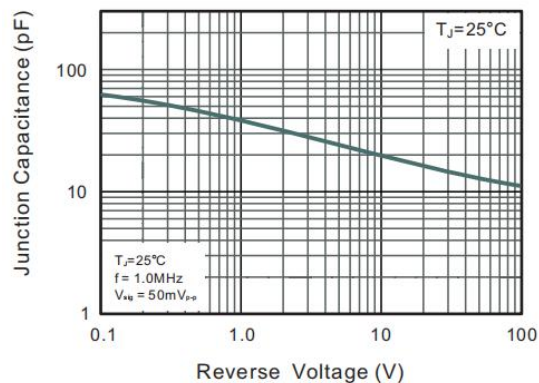
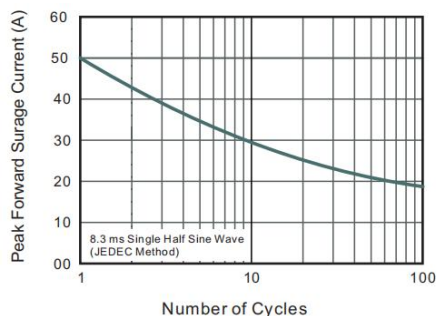


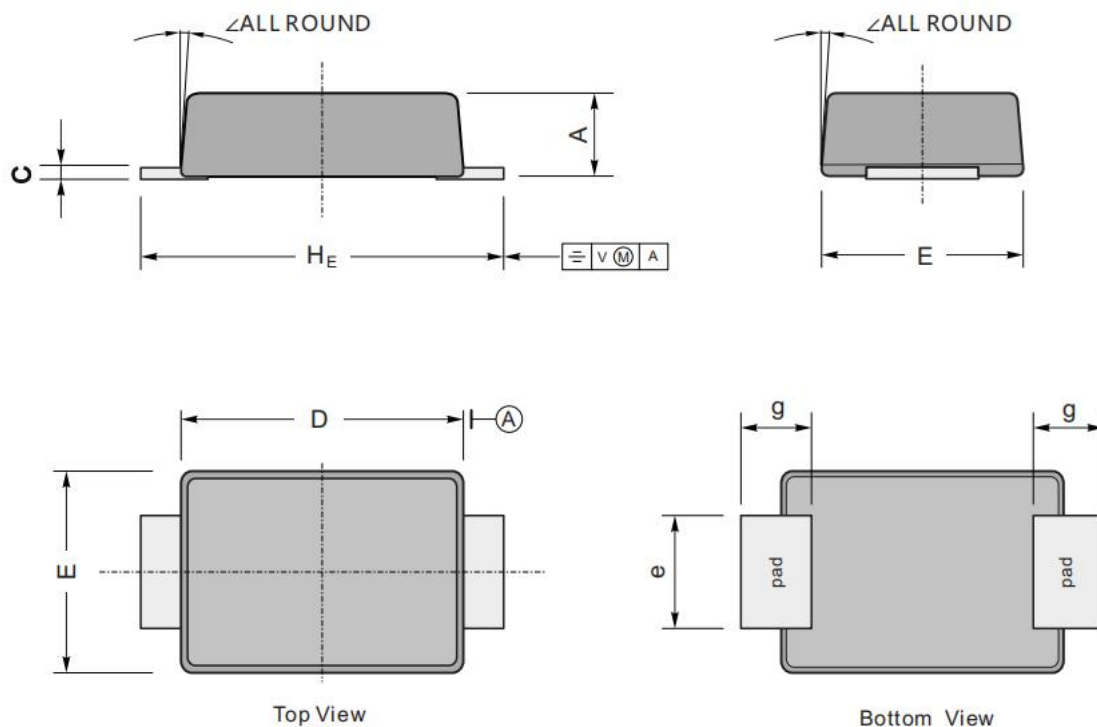
Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



Package Outline

Plastic surface mounted package; 2 leads

SMAF



UNIT		A	C	D	E	e	g	H _E	∠
mm	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	47	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size

